

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20150123003 Qualification of Hitachi as Additional Assembly/Test location for Select Devices in the DCU package Change Notification / Sample Request

Date: 1/26/2015

To: Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team SC Business Services

20150123003 Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TCA9406DCUR	null
TS5A3359DCUR	null
TS5A3359DCUT	null
TXB0102DCUR	null
TXB0102DCUT	null

Technical details of this Product Change follow on the next page(s).

PCN N	PCN Number: 20150123003 PCN Date: 1/26/2015								1/26/2015		
Title:	Qualification of HIT as Additional Assembly/Test location for Select Devices in the DCU package										
Customer Contact: PCN Manager					D	Dept: Quality Services					
Proposed 1 st Ship Date: 04/26/201				1/26/2015		Ferimated Sample Availability:					e provided on request
Chang	Change Type:										
\triangle	Assembly Sit	e		Assembl	уΡ	rocess		\boxtimes	Assembly Materials		
	Design			Electrica	l Sp	pecificat	ion		Mechanical Specification		
	est Site			Packing/	Packing/Shipping/Labeling				Test Process		
V	Wafer Bump	Site		Wafer Bu	Wafer Bump Material				Wafer Bump Process		
V	Wafer Fab Si	te		Wafer Fa	Wafer Fab Materials Wafer Fab Proces					roces	SS
	☐ Part number change										
	PCN Details										
Descri	Description of Change:										
	·										

Texas Instruments is pleased to announce the qualification of Hitachi as an alternate Assembly and Test site for the devices listed below. Device construction differences are noted as follows:

What	Hana Thailand	Hitachi
Mount Compound	SID#400154	SID#RZ241C
Mold Compound	SID#450207	SID#RM500F
Lead Finish	NiPdAu	Matte Sn

Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.

Upon expiry of this PCN TI will combine lead free solutions in a single <u>standard part number</u>, for example; <u>SN74AVCH2T45DCUR</u> – can ship with both Matte Sn and NiPdAu/Ag.

Example:

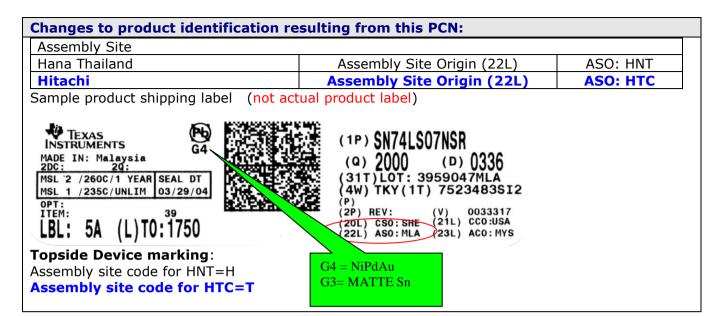
- Customer order for 7500units of SN74AVCH2T45DCUR with 2500 units SPQ (Standard Pack Quantity per Reel).
- TI can satisfy the above order in one of the following ways.
 - I. 3 Reels of NiPdAu finish.
 - II. 3 Reels of Matte Sn finish
 - III. 2 Reels of Matte Sn and 1 reel of NiPdAu finish.
 - IV. 2 Reels of NiPdAu and 1 reel of Matte Sn finish.

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None



Product Affected			
SN74AVCH2T45DCUR	TCA9406DCUR	TS5A3359DCUT	TXB0102DCUT
SN74AVCH2T45DCUT	TS5A3359DCUR	TXB0102DCUR	

Qualification Report

A-T site Transfer: TXB0102DCUR, TCA9406DCUR, SN74AVCH2T45DCUR, and TS5A3359DCUR (HNT to HIT)

Attributes	Qual Device: SN74AVCH2T45DCUR	Qual Device: TCA9406DCUR	Qual Device: TS5A3359DCUR	Qual Device: TXB0102DCUR	QBS Package: SN74LVC2G125DCUR	QBS Package: SN74LVC2G74DCUR	QBS Package: SN74CB3Q3306ADCUR
Assembly Site	HIT	HIT	HIT	HIT	HITACHI-RENESAS	HITACHI-RENESAS	HITACHI-RENESAS
Package Family		-	-		-	-	-
Flammability Rating	-		-	-	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Site	FFAB	FFAB	FFAB	FFAB	FFAB	FFAB	FFAB
Wafer Fab Process	ASLC10/P9705	ASLC10/P9785	ASLC10/P9785	ASLC10/P9785	ASL3C	ASL3C	ACTPI
- OBS: Qual By Similarity							

⁻ Qual Devices qualified at LEVEL1-260C: SN74AVCH2T45DCUR, TCA9406DCUR, TS5A3359DCUR, TXB0102DCUR

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

1									
Туре	Test Name / Condition	Duration	Qual Device: SN74AVCH2T45DCUR	Qual Device: TCA9406DCUR	Qual Device: TS5A3359DCUR	Qual Device: TXB0102DCUR	QBS Package: SN74LVC2G125DCUR	QBS Package: SN74LVC2G74DCUR	QBS Package: SN74CB3Q3306ADCUR
HAST	Biased HAST, 130C/85%RH	96 Hours		-	-	-		3/231/0	-
AC	Autoclave 121C	96 Hours	-	-	-	-	-		-
	Unbiased HAST 130C/85%RH	96 Hours	-	-	-	-	-	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles		-	-	-	-	3/231/0	3/231/0
HTSL	High Temp. Storage Bake, 170C	420 Hours		-	-	-	-	3/231/0	-
HTSL		500 Hours	-	-	-	-	-	-	-
TS	Thermal Shock-65/150C	500 Cycles	-	-	-	-	-	3/231/0	-
	Life Test, 150C	300 Hours	-	-	-	-	-	3/231/0	-
WBS	Bond Shear	Wires	-	-	-	-	-	-	-
WBP	Bond Pull	Wires	-	-	-	-	-	-	-
SD	Solderability	Post 8 Hours Steam Age	-	-	-	-	-	3/66/0	-
PD	Physical Dimensions		-	-	-	-	-	3/15/0	-
LI	Lead Fatigue	Leads	-	-	-	-	-	3/66/0	-
LI	Lead Pull	Leads	-	-	-	-	-	3/66/0	-
HBM	ESD - HBM	2000 V	-	-	-	-	-	-	-
HBM	ESD - HBM	2500 V							
CDM	ESD - CDM	750 V	-	-	-	-	-	-	-
CDM	ESD - CDM	1000 V							
CDM	ESD - CDM	1500 V							
LU	Latch-up	(per JESD78)	-	-	-	-	-		-
ED	Auto Electrical Distributions	Cpk>1.67 Room, hot, and cold test		-		-	-		-
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	Pass	-	-	-
		Wires	-	-	-	-	-	3/231/0	3/231/0
	Flammability (IEC 695-2-2)		-	-	-	-	-	3/15/0	-
	Flammability (UL 94V-0)		-	-	-	-	-	3/15/0	-
FLAM	Flammability (UL-1694)		-	-	-	-	-	3/15/0	-

FLAM [Flammability (UL-1694) — Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTDL options based on an activation energy of 0.7 eV: 125/C14 Hours, 140/C480 Hours, 150/C300 Hours, and 155/C240 Hours
- The following are equivalent THSL options based on an activation energy of 0.7 eV: 150/C14 Hours, and 170/C420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55/C125/C700 Cycles and -85/C150/C500 Cycles
- Qualify and Environmental data is available at 17ts external Veb size in http://www.ticomomental data is available at 17ts external Veb size in http://www.ticomomental data is available at 17ts external Veb size in http://www.ticomomental data is available at 17ts external Veb size in http://www.ticomomental data is available at 17ts external Veb size in http://www.ticomomental data is available at 17ts external Veb size in http://www.ticomomental data is available at 17ts external Veb size in http://www.ticomomental.

Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

Texas Instruments, Inc.

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com